

INFORMATION DISCLOSURE STATEMENT

FORM PTO - 1449

ATTORNEY DOCKET NO.: ASC-044C1

APPLICANT(S): Fitzgerald et al.

SERIAL NO.: 10/611,739

FILING DATE: July 1, 2003 GROUP: 2818

U.S. PATENT DOCUMENTS

A1 A2 A3 A4 A5 A6 A7 A8	2001/0003364 2002/0100942 2002/0043660 2002/0096717 2002/0123167 2002/0123183 2002/0123197	06/14/2001 08/01/2002 04/18/2002 07/25/2002 09/05/2002	Sugawara et al. Fitzgerald et al. Yamazaki et al. Chu et al. Fitzgerald					
A3 A4 A5 A6 A7	2002/0043660 2002/0096717 2002/0123167 2002/0123183	04/18/2002 07/25/2002 09/05/2002	Yamazaki et al. Chu et al. Fitzgerald					
A4 A5 A6 A7	2002/0096717 2002/0123167 2002/0123183	07/25/2002	Chu et al. Fitzgerald					
A5 A6 A7	2002/0123167 2002/0123183	09/05/2002	Fitzgerald					1
A6 A7	2002/0123183							
A7		09/05/2002	m: 11					
	2002/0123197	1	Fitzgerald					
A8		09/05/2002	Fitzgerald et al.					
	2002/0125471	09/12/2002	Fitzgerald et al.					
A9	2002/0125497	09/12/2002	Fitzgerald					
A10	2002/0140031	10/03/2002	Rim					
All	2002/0168864	11/14/2002	Cheng et al.					
A12	2003/0003679	01/02/2003	Doyle et al.					
A13	2003/0013323	01/16/2003	Hammond et al.					
A14	2003/0025131	02/06/2003	Lee et al.					
A15	2003/0057439	03/27/2003	Fitzgerald					
A16	4,010,045	03/01/1977	Ruehrwein					
A17	4,710,788	12/01/1987	Dämbkes et al.					
A18	4,990,979	02/05/1991	Otto					
A19	4,994,866	02/01/1991	Awano					
A20	4,997,776	03/05/1991	Harame et al.					
A21	5,013,681	05/07/1991	Godbey et al.					
	A99 A10 A11 A12 A13 A14 A15 A16 A17 A18 A19	A9 2002/0125497 A10 2002/0140031 A11 2002/0168864 A12 2003/0003679 A13 2003/0013323 A14 2003/0025131 A15 2003/0057439 A16 4,010,045 A17 4,710,788 A18 4,990,979 A19 4,994,866 A20 4,997,776 A21 5,013,681	A9 2002/0125497 09/12/2002 A10 2002/0140031 10/03/2002 A11 2002/0168864 11/14/2002 A12 2003/0003679 01/02/2003 A13 2003/0013323 01/16/2003 A14 2003/0025131 02/06/2003 A15 2003/0057439 03/27/2003 A16 4,010,045 03/01/1977 A17 4,710,788 12/01/1987 A18 4,990,979 02/05/1991 A19 4,994,866 02/01/1991 A20 4,997,776 03/05/1991 A21 5,013,681 05/07/1991	A9 2002/0125497 09/12/2002 Fitzgerald A10 2002/0140031 10/03/2002 Rim A11 2002/0168864 11/14/2002 Cheng et al. A12 2003/0003679 01/02/2003 Doyle et al. A13 2003/0013323 01/16/2003 Hammond et al. A14 2003/0025131 02/06/2003 Lee et al. A15 2003/0057439 03/27/2003 Fitzgerald A16 4,010,045 03/01/1977 Ruehrwein A17 4,710,788 12/01/1987 Dämbkes et al. A18 4,990,979 02/05/1991 Otto A19 4,994,866 02/01/1991 Awano A20 4,997,776 03/05/1991 Harame et al. A21 5,013,681 05/07/1991 Godbey et al.	A9 2002/0125497 09/12/2002 Fitzgerald A10 2002/0140031 10/03/2002 Rim A11 2002/0168864 11/14/2002 Cheng et al. A12 2003/0003679 01/02/2003 Doyle et al. A13 2003/0013323 01/16/2003 Hammond et al. A14 2003/0025131 02/06/2003 Lee et al. A15 2003/0057439 03/27/2003 Fitzgerald A16 4,010,045 03/01/1977 Ruehrwein A17 4,710,788 12/01/1987 Dämbkes et al. A18 4,990,979 02/05/1991 Otto A19 4,994,866 02/01/1991 Awano A20 4,997,776 03/05/1991 Harame et al. A21 5,013,681 05/07/1991 Godbey et al.	A9 2002/0125497 09/12/2002 Fitzgerald A10 2002/0140031 10/03/2002 Rim A11 2002/0168864 11/14/2002 Cheng et al. A12 2003/0003679 01/02/2003 Doyle et al. A13 2003/0013323 01/16/2003 Hammond et al. A14 2003/0025131 02/06/2003 Lee et al. A15 2003/0057439 03/27/2003 Fitzgerald A16 4,010,045 03/01/1977 Ruehrwein A17 4,710,788 12/01/1987 Dämbkes et al. A18 4,990,979 02/05/1991 Otto A19 4,994,866 02/01/1991 Awano A20 4,997,776 03/05/1991 Harame et al. A21 5,013,681 05/07/1991 Godbey et al.	A9 2002/0125497 09/12/2002 Fitzgerald A10 2002/0140031 10/03/2002 Rim A11 2002/0168864 11/14/2002 Cheng et al. A12 2003/0003679 01/02/2003 Doyle et al. A13 2003/0013323 01/16/2003 Hammond et al. A14 2003/0025131 02/06/2003 Lee et al. A15 2003/0057439 03/27/2003 Fitzgerald A16 4,010,045 03/01/1977 Ruehrwein A17 4,710,788 12/01/1987 Dämbkes et al. A18 4,990,979 02/05/1991 Otto A19 4,994,866 02/01/1991 Awano A20 4,997,776 03/05/1991 Harame et al. A21 5,013,681 05/07/1991 Godbey et al.	A9 2002/0125497 09/12/2002 Fitzgerald A10 2002/0140031 10/03/2002 Rim A11 2002/0168864 11/14/2002 Cheng et al. A12 2003/0003679 01/02/2003 Doyle et al. A13 2003/0013323 01/16/2003 Hammond et al. A14 2003/0025131 02/06/2003 Lee et al. A15 2003/0057439 03/27/2003 Fitzgerald A16 4,010,045 03/01/1977 Ruehrwein A17 4,710,788 12/01/1987 Dämbkes et al. A18 4,990,979 02/05/1991 Otto A19 4,994,866 02/01/1991 Awano A20 4,997,776 03/05/1991 Harame et al. A21 5,013,681 05/07/1991 Godbey et al.

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ATTORNEY DOCKET NO.: ASC-044C1

APPLICANT(S): Fitzgerald et al.

SERIAL NO.: 10/611,739

	·		USI	PATENT	DOCUMENTS						
EXAM. INIT.		DOCUMENT NUMBER	DATE	NAME	DOCOMENTS		ASS	- 1	SU	B ASS	FILING DATE IF
M.	A22	5,155,571	10/13/1992	Wang et	al.			1	T		
"	A23	5,166,084	11/24/1992	Pfiester				7	1		
	A24	5,177,583	01/05/1993	Endo et	al.			71	١		
	A25	5,202,284	04/13/1993	Kamins	et al.		Τ	Π	1		
	A26	5,207,864	05/04/1993	Bhat et d	ıl.			\prod			
	A27	5,208,182	05/04/1993	Narayan	et al.			П			
	A28	5,212,110	05/18/1993	Pfiester	et al.						
	A29	5,221,413	06/22/1993	Brasen e	t al.			\top			
	A30	5,241,197	08/31/1993	Murakar	mi <i>et al</i> .		П	1			
	A31	5,250,445	10/05/1993	Bean et	al.			T			
	A32	5,285,086	02/08/1994	Fitzgera	ld		I	\top			
	A33	5,291,439	03/01/1994	Kauffma	nn et al.			寸		\parallel	
	A34	5,298,452	03/29/1994	Meyerso	n			T			
	A35	5,310,451	05/10/1994	Tejwani	et al.			十		11	
	A36	5,316,958	05/31/1994	Meyerso	n			寸		#	
	A37	5,346,848	09/13/1994	Grupen-	Shemansky et al.			十			
	A38	5,374,564	12/20/1994	Bruel			1	\dashv		1	
+	A39	5,399,522	03/21/1995	Ohori						11	
1	A40	5,413,679	05/09/1995	Godbey						1	
	A41	5,426,069	06/20/1995	Selvaku	mar et al.			Ì		\top	
	A42	5,426,316	06/20/1995	Mohamr	nad	11				11	
1	A43	5,442,205	08/15/1995	Brasen e	t al.	\Box	T	\dashv		11	<u> </u>
_	A44	5,461,243	10/24/1995	Ek et al.		17		\dashv			
$\overline{}$	A45	5,461,250	10/24/1995	Burghar	tz et al.	11		\top	_	71	
Vic	A46	5,462,883	10/31/1995	Dennard	et al.	-1/				11	
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INFORMATION DISCLOSURE STATEMENT

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APPLICANT(S): Fitzgerald et al.

SERIAL NO.: 10/611,739

					FILING DAT	re: July	<i>1</i> 1,	2003	GR	OUP	: 2818
			U.S. I	PATENT	DOCUMEN	ITS				Ĺ	
EXAM.		DOCUMENT NUMBER	DATE	NAME			CL.	ASS	SU CL	B ASS	FILING DATE IF APPROPRIATE
1)//	A47	5,476,813	12/19/1995	Naruse				1			
, <u>, , , , , , , , , , , , , , , , , , </u>	A48	5,479,033	12/26/1995	Baca et	al.		T		T	\top	
1	A49	5,484,664	01/16/1996	Kitahara	et al.					\top	
	A50	5,523,243	06/04/1996	Mohami	mad		T			\top	
1	A51	5,523,592	06/04/1996	Nakagav	va et al.		T			1	
	A52	5,534,713	07/09/1996	Ismail e	ı al.		T	1			
	A53	5,536,361	07/16/1996	Kondo e	et al.		†	\top			
	A54	5,540,785	07/30/1996	Dennard	et al.		1		\prod		
1	A55	5,596,527	01/21/1997	Tomiok	a et al.		1				
	A56	5,617,351	04/01/1997	Bertin e	t al.			\top	\prod		
	A57	5,630,905	05/20/1997	Lynch e	t al.		1		\prod		
	A58	5,659,187	08/19/1997	Legoues	et al.				\sqcap		
	A59	5,683,934	11/04/1997	Candela	ria				\sqcap		
	A60	5,698,869	12/16/1997	Yoshim	i et al.	·		1			
	A61	5,714,777	02/03/1998	Ismail e	t al.			\parallel	T	1	
	A62	5,728,623	03/17/1998	Mori				1		1	
	A63	5,739,567	04/14/1998	Wong				1			
	A64	5,759,898	06/02/1998	Ek et al.				1		1	
	A65	5,777,347	07/07/1998	Bartelin	k					1	
	A66	5,786,612	07/28/1998	Otani et	al.					T	
	A67	5,792,679	08/11/1998	Nakato						\prod	
	A68	5,808,344	09/15/1998	Ismail e	t al.		7				
	A69	5,847,419	12/08/1998	Imai et	al.		7	1			
	A70	5,877,070	03/02/1999	Goesele	et al.		7			\	
M	A71	5,891,769	04/06/1999	Liaw et	al.		T				
EXAMINER L					DATE CON	ISIDERI	ED		-	Tw	ly-roof

FORM	I PTO –	1449		_	ATTORNEY D	OCKET NO.:	ASC-044	IC1		
INFO	RMATIC	N DISCLOSU	RE STATEMI	ENT	APPLICANT(S	s): Fitzgerald	et al.			
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					FILING DATE:	•	CDOID.	2010		
			***	D 4 (7772) Y77			GROUP.	2010		
	<u> </u>	T	- ₁		DOCUMENTS	·				
EXAM. INIT.		DOCUMENT NUMBER	DATE	NAME		CLASS	SUB CLASS	FILING DATE IF APPROPRIATE		
W	A72	5,906,708	05/25/1999	Robinso	n et al.	1	b			
1	A73	5,906,951	05/25/1999	Chu et a	l.					
\Box	A74	5,912,479	06/15/1999	Mori et	al.					
\vdash	A75	5,943,560	08/24/1999	Chang e	t al.	1 X	X			
	A76	5,963,817	10/05/1999	Chu et a	l.	1/\	/\			
	A77	5,966,622	10/12/1999	Levine e	t al.	1/-		\		
	A78	5,998,807	12/07/1999	Lustig e	t al.	V				
	A79	6,013,134	01/11/2000	Chu et a	l.		\			
	A80	6,033,974	03/07/2000	Henley 6	et al.		\	,		
	A81	6,033,995	03/07/2000	Muller		 	X			
	A82	6,058,044	05/02/2000	Sugiura	et al.					
	A83	6,059,895	05/09/2000	Chu et a	l.	1/-	· · · · ·			
	A84	6,074,919	06/13/2000	Gardner	et al.	1/	\			
	A85	6,096,590	08/01/2000	Chan et	al.					
	A86	6,103,559	08/15/2000	Gardner	et al.	17		/		
	A87	6,107,653	08/22/2000	Fitzgera	ld		X			
	A88	6,111,267	08/29/2000	Fischer e	et al.		/ \			
	A89	6,117,750	09/12/2000	Bensahe	l et al.		1			
	A90	6,130,453	10/10/2000	Mei et a	l.					
	A91	6,133,799	10/17/2000	Favors e	t al.	\neg	\ /			
	A92	6,140,687	10/31/2000	Shimom	ura et al.		1			
	A93	6,143,636	11/07/2000	Forbes e	t al.	1/\	A			
	A94	6,153,495	11/28/2000	Kub et a	ıl.					
00	A95	6,154,475	11/28/2000	Soref et	al.					
the	/ A96	6,160,303	12/12/2000	Fattarus	0	X				
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FORM 1	PTO – 1	449			ATTORNEY DO	CKET NO.:	ASC-044	‡C1
INFORM	OITAN	N DISCLOSU	RE STATEMI	ENT	APPLICANT(S):	Fitzgerald	et al.	
					SERIAL NO.: 10	0/611,739		
					FILING DATE:	July 1, 2003	GROUP:	: 2818
			U.S. 1	PATENT	DOCUMENTS			
EXAM. INIT.		DOCUMENT NUMBER	DATE	NAME		CLASS	SUB CLASS	FILING DATE I
Dle	A97	6,162,688	12/19/2000	Gardner	et al.		7	
	A98	6,184,111	02/06/2001	Henley	et al.		/	
	A99	6,191,007	02/20/2001	Matsui e	et al.		/	
1	A100	6,191,432	02/20/2001	Sugiyan	na et al.	/		
1	A101	6,194,722	02/27/2001	Fiorini e	et al.	1 /		
	A102	6,204,529	03/20/2001	Lung et	al.	1/		
+-	A103	6,207,977	03/27/2001	Augusto		1		
<u> </u>	A104	6,210,988	04/03/2001	Howe et al.			/	
	A105	6,218,677	04/17/2001	Broekae	rt		/	
	A106	6,232,138	05/15/2001	Fitzgera	ld et al.			
	A107	6,235,567	05/22/2001	Huang		/		
	A108	6,242,324	06/05/2001	Kub et d	ıl.			
	A109	6,249,022	06/19/2001	Lin et a	l.	/		*
	A110	6,251,755	06/26/2001	Furukav	va et al.	1/		
	A111	6,261,929	07/17/2001	Gehrke	et al.			
	A112	6,266,278	07/24/2001	Harari e	t al.			
1	A113	6,271,551	08/07/2001	Schmitz	et al.			
	A114	6,271,726	08/07/2001	Fransis	et al.	1 /		
	A1'15	6,291,321	09/18/2001	Fitzgera	ld	1/		
	A116	6,313,016	11/06/2001	Kibbel	et al.	1/		
1	A117	6,316,301	11/13/2001	Kant				,
	A118	6,323,108	11/27/2001	Kub et e	al.			_
	A119	6,329,063	12/11/2001	Lo et al		/		
1	A120	6,335,546	01/01/2002	Tsuda e	t al.	1		

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EXAMINER

FORM F	PTO - 1	449			ATTORNI	EY DOCK	CET NO.:	ASC-04	4C1		
INFORM	1ATIO	N DISCLOSU	RE STATEM	ENT	APPLICANT(S): Fitzgerald et al.						
					SERIAL N	O.: 10/6	11,739				
					FILING D	ATE: Jul	y 1, 2003	GROUP	: 2818		
-			U.S.	PATENT	DOCUMI	ENTS					
EXAM.		DOCUMENT	DATE	NAME	-		CLASS	SUB	1	G DATE IF	
INIT.	ļ	NUMBER						CLASS	APPR	OPRIATE	
lle	A122	6,350,993	02/26/2002	Chu et a			1	/	<u></u>		
	A123	6,368,733	04/09/2002	Nishina	ga						
	A124	6,372,356	04/16/2002	Thornto	n <i>et al</i> .						
	A125	6,399,970	06/04/2002	Kubo et	al.			\mathbb{X}			
	A126	6,403,975	06/11/2002	Brunner	et al.		/				
	A127	6,407,406	06/18/2002	Tezuka							
	A128	6,420,937	07/16/2002	Akatsuk	a et al.						
	A129	6,425,951	07/30/2002	Chu et a	ıl.		10				
	A130	6,429,061	08/06/2002	Rim				/			
	A131	6,521,041	02/18/2003	Wu et a	I.			\bigvee			
	A132	6,524,935	02/25/2003	Canaper	ri et al.						
	A133	6,555,839	04/29/2003	Fitzgera	ld						
	A134	6,573,126	06/03/2003	Cheng e	et al.		;				
	A135	6,583,015	06/24/2003	Fitzgera	ld et al.				-		
	A136	6,593,191	07/15/2003	Fitzgera	ld				05/16	/2001	
	A137	6,602,613	08/05/2003	Fitzgera	ıld			X	01/17	/2001	
	A138	6,649,480	11/18/2003	Fitzgera	ld et al.				06/19	/2001	
The	A139	6,682,965	01/27/2004	Noguch	i <i>et al</i> .			7	03/26	/1998	
			FOREI	GN PATI	NT DOCU	IMENTS	3				
EXAM. INIT.		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	FILING	ABST	RACT ′	ENGLISI LANG (Y/N)	
M	B1	41 01 167	07/23/1992	DE			i	N		Abstract only	
	B2	0 514 018	11/19/1992	EP				N		Y	
	В3	0 587 520	03/16/1994	EP				N		Υ	
Th	B4 <	0 683 522	11/22/1995	EP	1		T^{-}	N		Y	

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					SERIAL N	O.: 10/61	1,739		
					FILING D	ATE: July	y 1, 2003 (GROUP: 2818	
			FOREI	GN PATEN	VT DOCU	MENTS			
EXAM. INIT.	-	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	FILING DATE	ABSTRACT ONLY	ENGLISH LANG (Y/N)
1/2	B5	0 828 296	03/11/1998	EP				N	Y
***	B6	0 829 908	03/18/1998	EP			1	N	Y
	B7	0 838 858	04/29/1998	EP				N	N
	B8	1 020 900	07/19/2000	EP			//	N	Y
	В9	1 174 928	01/23/2002	EP		\ \ \	/	N	Y
	B10	2 701 599	03/21/1995	FR				N	Abstract only
	BII	2 342 777	04/19/2000	GB				Y	Y
	B12	4-307974	10/30/1992	JP				N	Abstract only
	B13	5-166724	07/02/1993	JР				N	Abstract only
	B14	6-177046	06/24/1994	JP				N	Abstract only
	B15	6-244112	09/02/1994	JP				Y	Y
	B16	6-252046	09/09/1994	JP				Y	Y
	B17	7-94420	04/07/1995	JР		/		N	Abstract only
\top	B18	7-106446	04/21/1995	JP				N	Abstract only
	B19	7-240372	09/12/1995	JP	/			N	Abstract only
	B20	10-270685	10/09/1998	JP			<u> </u>	N	Y
	B21	11-233744	08/27/1999	JP			-	N	Abstract only
	B22	2000-021783	01/21/2000	JP			V	N	Y
	B23	2000-031491	01/28/2000	JP				N	Y
	B24	2001-319935	11/16/2001	JP				N	Y
M	B25	2002-076334	03/15/2002	JP	1 /	1		N	Y
1/4	B26	2002/164520	06/07/2002	JP				N	Y
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FORM	 М РТО –	1449			ATTORN	EY DOCK	ET NO.: A	ASC-044C1	········		
INFO	RMATIO	ON DISCLOSU	RE STATEM	IENT	APPLICA	NT(S): F	itzgerald <i>et</i>	al.			
					1						
					SERIAL NO.: 10/611,739						
		<u> </u>		<u>-</u>	FILING D	ATE: Jul	y 1, 2003 C	GROUP: 2818	3		
			FOREI	GN PATE	NT DOCU	IMENTS					
EXAM	i.	DOCUMENT	DATE	COUNTRY	CLASS	SUB	FILING	ABSTRACT	ENGLISH		
INIT.		NUMBER		CODE		CLASS	DATE	ONLY	LANG (Y/N)		
1	B27	2002-289533	10/04/2002	JP	+			N	Y		
lle	B28	98/59365	12/30/1998	wo	+	 	 	N	Y .		
\vdash	B29	99/53539	10/21/1999	wo	-			N	Y		
 	B30	00/48239	08/17/2000	wo		\	 / 	N	Y		
	B31	00/48239	09/14/2000	wo	+	\vdash	\longleftarrow	N	Y		
-	B32	01/022482	03/29/2001	wo	-		\nearrow	N	Y		
		01/022482	07/26/2001	wo				N	Y		
 - -	B33	***************************************				 /-		N	Y		
	B34	01/93338	12/06/2001	WO	_	/	ļ		Y		
	B35	01/99169	12/27/2001	wo	1	<u> </u>	ļ	N	<u> </u>		
	B36	02/13262		02/14/2002 WO N Y							
	B37	02/15244	02/21/2002	wo	/			N	Y		
	B38	02/27783	04/04/2002	wo				N	Y		
	B39	02/47168	06/13/2002	wo		<u> </u>	X	N	Y		
	B40	02/071488	09/12/2002	wo				N	Y		
	B41	02/071491	09/12/2002	wo				N	Y		
SV	B42	02/071495	09/12/2002	wo		1		N	Y		
Ki	/ B43	02/082514	10/17/2002	wo	1			N	Y		
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